

10 kPa On-Chip Temperature Compensated and Calibrated Silicon Pressure Sensors

The MPX2010 series silicon piezoresistive pressure sensors provide a very accurate and linear voltage output directly proportional to the applied pressure. These sensors house a single monolithic silicon die with the strain gauge and thin film resistor network integrated. The sensor is laser trimmed for precise span, offset calibration and temperature compensation.

Features

- Temperature Compensated over 0°C to +85°C
- Ratiometric to Supply Voltage
- Differential and Gauge Options
- Available in Easy-to-Use Tape & Reel

MPX2010 Series

0 to 10 kPa (0 to 1.45 psi)
25 mV Full Scale
(Typical)

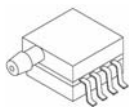
Application Examples

- Respiratory Diagnostics
- Air Movement Control
- Controllers
- Pressure Switching

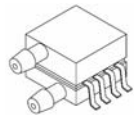
ORDERING INFORMATION

Device Name	Package Options	Case No.	# of Ports			Pressure Type			Device Marking
			None	Single	Dual	Gauge	Differential	Absolute	
Small Outline Package (MPXV2010 Series)									
MPXV2010GP	Tray	1369		•		•			MPXV2010GP
MPXV2010DP	Tray	1351			•		•		MPXV2010DP
Unibody Package (MPX2010 Series)									
MPX2010D	Tray	344	•					•	MPX2010D
MPX2010DP	Tray	344C			•		•		MPX2010DP
MPX2010GP	Tray	344B		•		•			MPX2010GP
MPX2010GS	Tray	344E		•		•			MPX2010D
MPX2010GSX	Tray	344F		•		•			MPX2010D
MPAK Package (MPXM2010 Series)									
MPXM2010D	Rail	1320	•					•	MPXM2010D
MPXM2010DT1	Tape and Reel	1320	•					•	MPXM2010D
MPXM2010GS	Rail	1320A		•		•			MPXM2010GS
MPXM2010GST1	Tape and Reel	1320A		•		•			MPXM2010GS

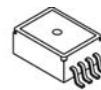
SMALL OUTLINE PACKAGES



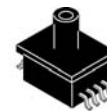
MPXV2010GP
CASE 1369-01



MPXV2010DP
CASE 1351-01



MPXM2010D/DT1
CASE 1320-02



MPXM2010GS/GST1
CASE 1320A-02

UNIBODY PACKAGES



MPX2010D
CASE 344-15



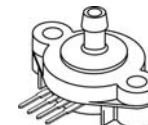
MPX2010GP
CASE 344B-01



MPX2010DP
CASE 344C-01



MPX2010GS
CASE 344E-01



MPX2010GSX
CASE 344F-01

Operating Characteristics

Table 1. Operating Characteristics ($V_S = 10 V_{DC}$, $T_A = 25^\circ C$ unless otherwise noted, $P_1 > P_2$)

Characteristic	Symbol	Min	Typ	Max	Units
Pressure Range ⁽¹⁾	P_{OP}	0	—	10	kPa
Supply Voltage ⁽²⁾	V_S	—	10	16	V_{DC}
Supply Current	I_O	—	6.0	—	mAdc
Full Scale Span ⁽³⁾	V_{FSS}	24	25	26	mV
Offset ⁽⁴⁾	V_{OFF}	-1.0	—	1.0	mV
Sensitivity	$\Delta V/\Delta P$	—	2.5	—	mV/kPa
Linearity	—	-1.0	—	1.0	% V_{FSS}
Pressure Hysteresis (0 to 10 kPa)	—	—	± 0.1	—	% V_{FSS}
Temperature Hysteresis (-40°C to +125°C)	—	—	± 0.5	—	% V_{FSS}
Temperature Coefficient on Full Scale Span	TCV_{FSS}	-1.0	—	1.0	% V_{FSS}
Temperature Coefficient on Offset	TCV_{OFF}	-1.0	—	1.0	mV
Input Impedance	Z_{IN}	1300	—	2550	Ω
Output Impedance	Z_{OUT}	1400	—	3000	Ω
Response Time ⁽⁵⁾ (10% to 90%)	t_R	—	1.0	—	ms
Warm-Up Time	—	—	20	—	ms
Offset Stability ⁽⁶⁾	—	—	± 0.5	—	% V_{FSS}

- 1.0 kPa (kiloPascal) equals 0.145 psi.
- Device is ratiometric within this specified excitation range. Operating the device at a different range may induce additional error due to device self-heating.
- Full Scale Span (V_{FSS}) is defined as the algebraic difference between the output voltage at full rated pressure and the output voltage at the minimum rated pressure.
- Offset (V_{OFF}) is defined as the output voltage at the minimum rated pressure.
- Response Time is defined as the time for the incremental change in the output to go from 10% to 90% of its final value when subjected to a specified step change in pressure.
- Offset stability is the product's output deviation when subjected to 1000 hours of Pulsed Pressure, Temperature Cycling with Bias Test.

Maximum Ratings

Table 2. Maximum Ratings⁽¹⁾

Rating	Symbol	Value	Unit
Maximum Pressure (P1 > P2)	P_{MAX}	75	kPa
Burst Pressure (P1 > P2)	P_{BURST}	100	kPa
Storage Temperature	T_{STG}	-40 to +125	°C
Operating Temperature	T_A	-40 to +125	°C

1. Exposure beyond the specified limits may cause permanent damage or degradation to the device.

Voltage Output versus Applied Differential Pressure

The output voltage of the differential or gauge sensor increases with increasing pressure applied to the pressure side (P1) relative to the vacuum side (P2). Similarly, output voltage increases as increasing vacuum is applied to the vacuum side (P2) relative to the pressure side (P1).

Figure 1. shows a block diagram of the internal circuitry on the stand-alone pressure sensor chip.

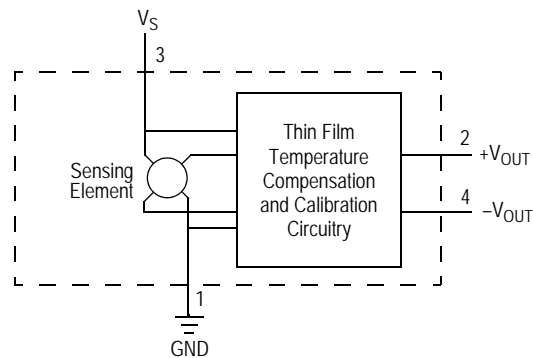


Figure 1. Temperature Compensated and Calibrated Pressure Sensor Schematic

On-Chip Temperature Compensation and Calibration

Figure 2. shows the output characteristics of the MPX2010 series at 25°C. The output is directly proportional to the differential pressure and is essentially a straight line.

The effects of temperature on full scale span and offset are very small and are shown under Operating Characteristics.

This performance over temperature is achieved by having both the shear stress strain gauge and the thin-film resistor circuitry on the same silicon diaphragm. Each chip is dynamically laser trimmed for precise span and offset calibration and temperature compensation.

Figure 3. illustrates the differential/gauge die in the basic chip carrier (Case 344). A silicone gel isolates the die surface and wire bonds from the environment, while allowing the pressure signal to be transmitted to the silicon diaphragm.

The MPX2010 series pressure sensor operating characteristics and internal reliability and qualification tests are based on use of dry air as the pressure media. Media other than dry air may have adverse effects on sensor

performance and long term reliability. Contact the factory for information regarding media compatibility in your application.

LINEARITY

Linearity refers to how well a transducer's output follows the equation: $V_{out} = V_{off} + \text{sensitivity} \times P$ over the operating pressure range. There are two basic methods for calculating nonlinearity: (1) end point straight line fit (see Figure 4.) or (2) a least squares best line fit. While a least squares fit gives the "best case" linearity error (lower numerical value), the calculations required are burdensome.

Conversely, an end point fit will give the "worst case" error (often more desirable in error budget calculations) and the calculations are more straightforward for the user.

Freescale's specified pressure sensor linearities are based on the end point straight line method measured at the midrange pressure.

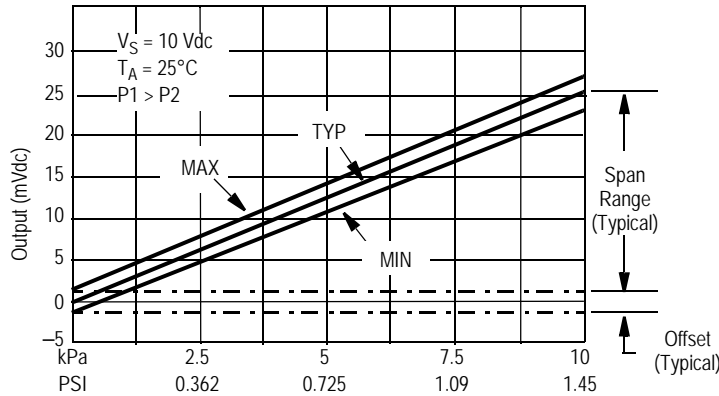


Figure 2. Output vs. Pressure Differential

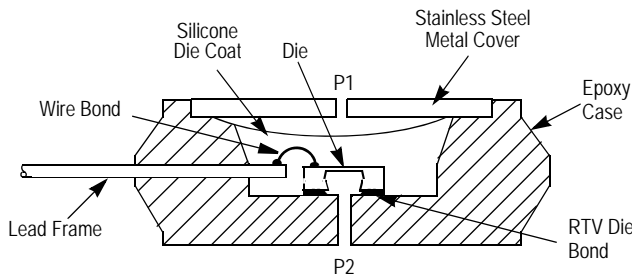


Figure 3. Unibody Package: Cross Sectional Diagram (not to scale)

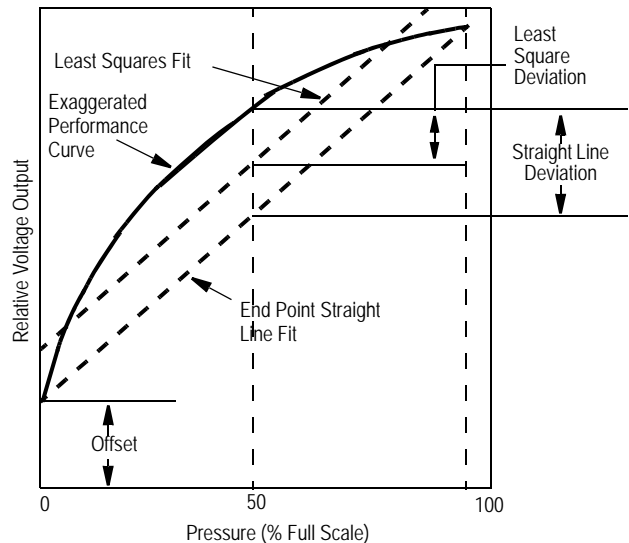


Figure 4. Linearity Specification Comparison

PRESSURE (P1)/VACUUM (P2) SIDE IDENTIFICATION TABLE

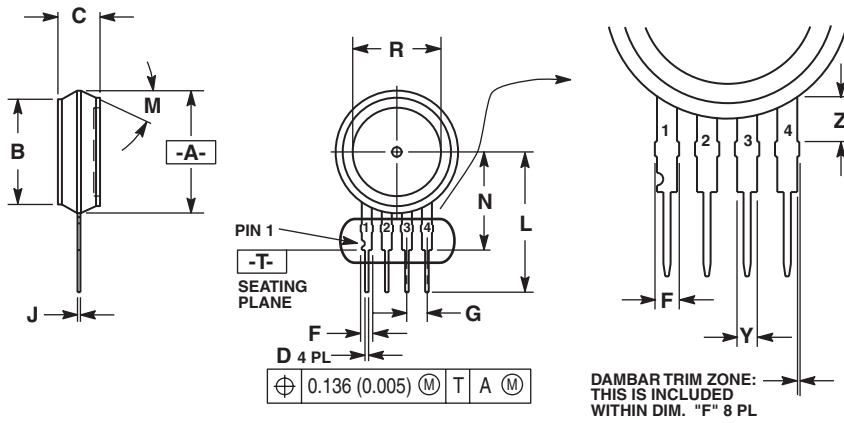
Freescale designates the two sides of the pressure sensor as the Pressure (P1) side and the Vacuum (P2) side. The Pressure (P1) side is the side containing silicone gel which isolates the die from the environment. The pressure sensor is designed to operate with positive differential pressure applied, $P1 > P2$.

The Pressure (P1) side may be identified by using the following table.

Table 3. Pressure (P1) Side Delineation

Part Number	Case Type	Pressure (P1) Side Identifier
MPX2010D	344	Stainless Steel Cap
MPX2010DP	344C	Side with Part Marking
MPX2010GP	344B	Side with Port Attached
MPX2010GS	344E	Side with Port Attached
MPX2010GSX	344F	Side with Port Attached
MPXV2010GP	1369	Side with Port Attached
MPXV2010DP	1351	Side with Part Marking
MPXM2010D/DTI	1320	Side with Part Marking
MPXM2010GS/GSTI	1320A	Side with Port Attached

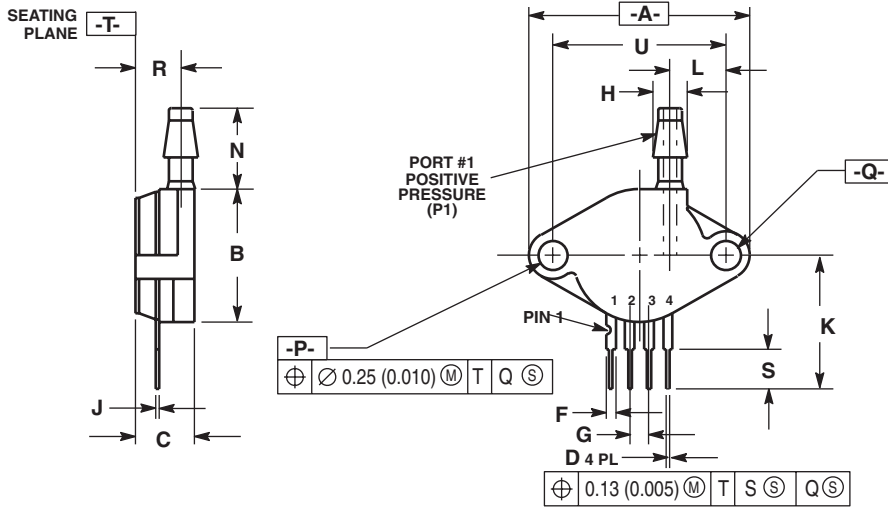
PACKAGE DIMENSIONS



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION -A- IS INCLUSIVE OF THE MOLD STOP RING. MOLD STOP RING NOT TO EXCEED 16.00 (0.630).

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.595	0.630	15.11	16.00
B	0.514	0.534	13.06	13.56
C	0.200	0.220	5.08	5.59
D	0.016	0.020	0.41	0.51
F	0.048	0.064	1.22	1.63
G	0.100 BSC		2.54 BSC	
J	0.014	0.016	0.36	0.40
L	0.695	0.725	17.65	18.42
M	30° NOM		30° NOM	
N	0.475	0.495	12.07	12.57
R	0.430	0.450	10.92	11.43
Y	0.048	0.052	1.22	1.32
Z	0.106	0.118	2.68	3.00

CASE 344-15
ISSUE AA
UNIBODY PACKAGE

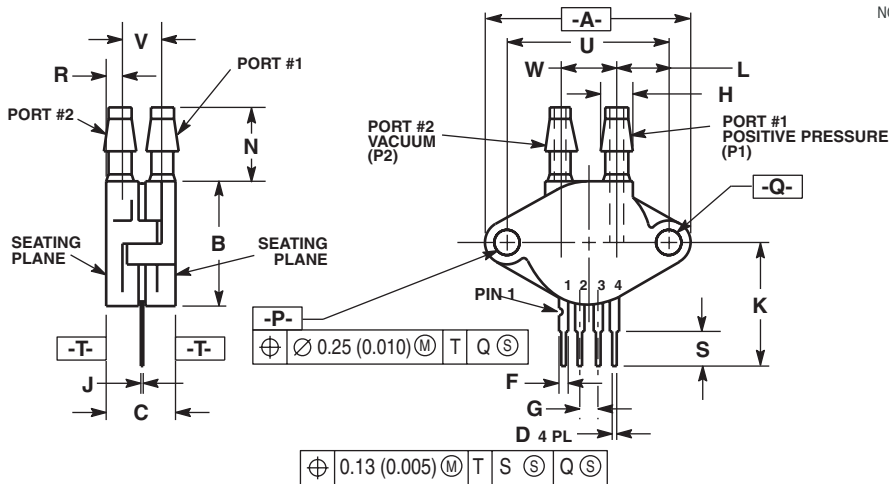


- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	1.145	1.175	29.08	29.85
B	0.685	0.715	17.40	18.16
C	0.305	0.325	7.75	8.26
D	0.016	0.020	0.41	0.51
F	0.048	0.064	1.22	1.63
G	0.100 BSC		2.54 BSC	
H	0.182	0.194	4.62	4.93
J	0.014	0.016	0.36	0.41
K	0.695	0.725	17.65	18.42
L	0.290	0.300	7.37	7.62
N	0.420	0.440	10.67	11.18
P	0.153	0.159	3.89	4.04
Q	0.153	0.159	3.89	4.04
R	0.230	0.250	5.84	6.35
S	0.220	0.240	5.59	6.10
U	0.910 BSC		23.11 BSC	

CASE 344B-01
ISSUE B
UNIBODY PACKAGE

PACKAGE DIMENSIONS

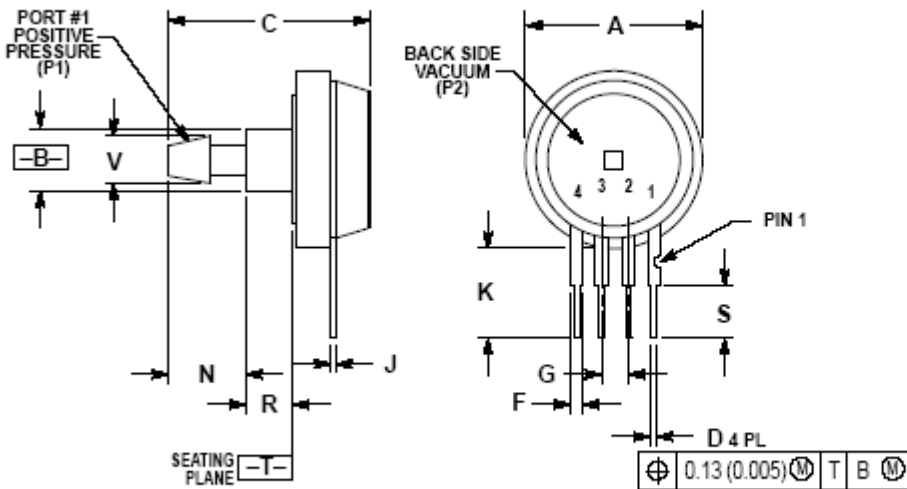


- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	1.145	1.175	29.08	29.85
B	0.685	0.715	17.40	18.16
C	0.405	0.435	10.29	11.05
D	0.016	0.020	0.41	0.51
F	0.048	0.064	1.22	1.63
G	0.100 BSC		2.54 BSC	
H	0.182	0.194	4.62	4.93
J	0.014	0.016	0.36	0.41
K	0.695	0.725	17.65	18.42
L	0.290	0.300	7.37	7.62
N	0.420	0.440	10.67	11.18
P	0.153	0.159	3.89	4.04
Q	0.153	0.159	3.89	4.04
R	0.063	0.083	1.60	2.11
S	0.220	0.240	5.59	6.10
U	0.910 BSC		23.11 BSC	
V	0.248	0.278	6.30	7.06
W	0.310	0.330	7.87	8.38

- STYLE 1:
 PIN 1: GROUND
 2. + OUTPUT
 3. + SUPPLY
 4. - OUTPUT

CASE 344C-01
 ISSUE B
 UNIBODY PACKAGE



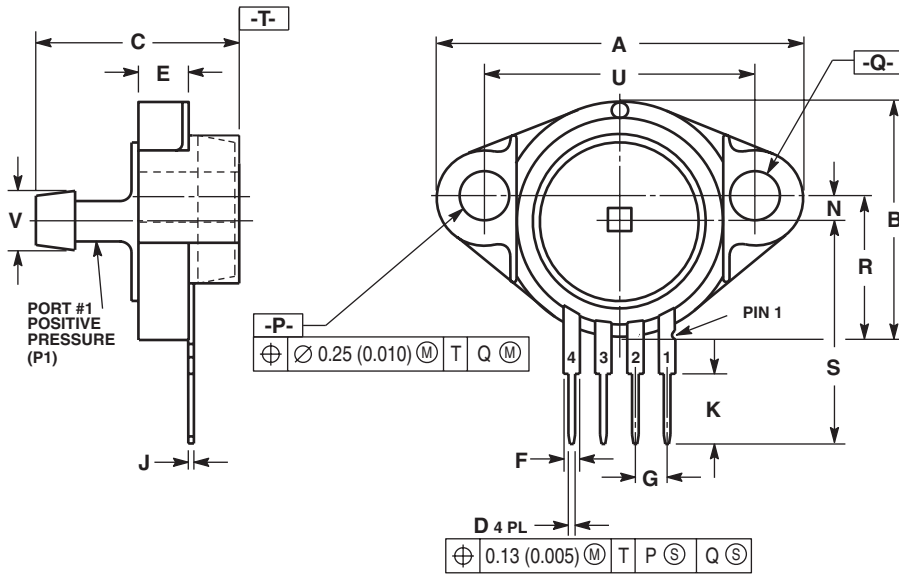
- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.890	0.720	17.53	18.28
B	0.245	0.255	6.22	6.48
C	0.790	0.820	19.81	20.82
D	0.018	0.020	0.41	0.51
F	0.048	0.064	1.22	1.63
G	0.100 BSC		2.54 BSC	
J	0.014	0.016	0.36	0.41
K	0.345	0.375	8.78	9.53
N	0.300	0.310	7.62	7.87
R	0.178	0.186	4.52	4.72
S	0.220	0.240	5.59	6.10
V	0.182	0.194	4.62	4.93

- STYLE 1:
 PIN 1: GROUND
 2. + OUTPUT
 3. + SUPPLY
 4. - OUTPUT

CASE 344E-01
 ISSUE B
 UNIBODY PACKAGE

PACKAGE DIMENSIONS



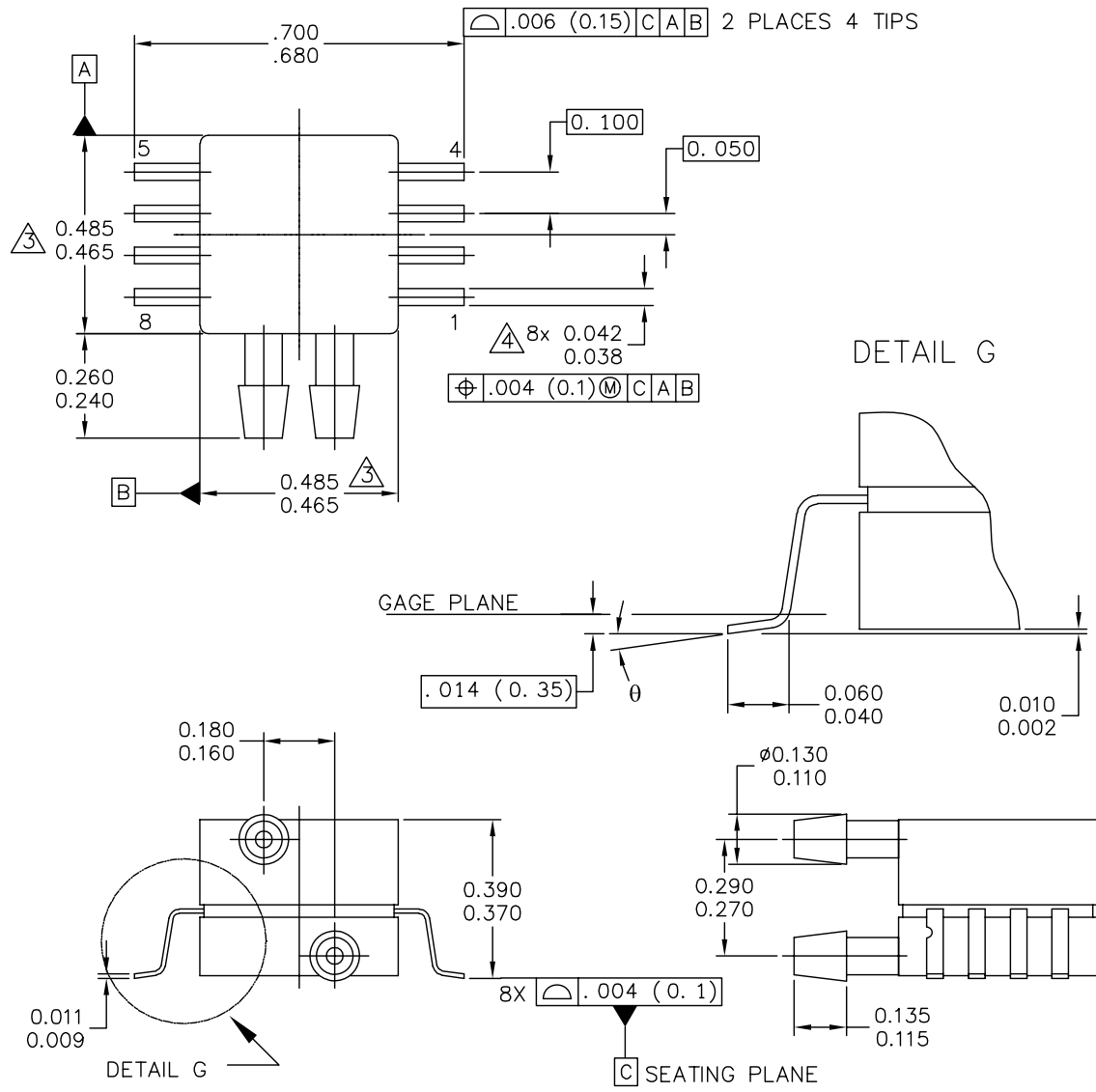
- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	1.080	1.120	27.43	28.45
B	0.740	0.760	18.80	19.30
C	0.630	0.650	16.00	16.51
D	0.016	0.020	0.41	0.51
E	0.160	0.180	4.06	4.57
F	0.048	0.064	1.22	1.63
G	0.100 BSC		2.54 BSC	
J	0.014	0.016	0.36	0.41
K	0.220	0.240	5.59	6.10
N	0.070	0.080	1.78	2.03
P	0.150	0.160	3.81	4.06
Q	0.150	0.160	3.81	4.06
R	0.440	0.460	11.18	11.68
S	0.695	0.725	17.65	18.42
U	0.840	0.860	21.34	21.84
V	0.182	0.194	4.62	4.92

- STYLE 1:
1. GROUND
 2. V (+) OUT
 3. V SUPPLY
 4. V (-) OUT

CASE 344F-01
ISSUE B
UNIBODY PACKAGE

PACKAGE DIMENSIONS



© FREESCALE SEMICONDUCTOR, INC. ALL RIGHTS RESERVED.	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: 8 LD SNSR, DUAL PORT	DOCUMENT NO: 98ASA99255D	REV: A
	CASE NUMBER: 1351-01	27 JUL 2005
	STANDARD: NON-JEDEC	

**CASE1351-01
ISSUE A
SMALL OUTLINE PACKAGE**

PACKAGE DIMENSIONS

NOTES:

1. CONTROLLING DIMENSION: INCH
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH AND PROTRUSIONS SHALL NOT EXCEED .006 PER SIDE.
4. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE .008 MAXIMUM.

STYLE 1:

PIN 1: GND
 PIN 2: +Vout
 PIN 3: Vs
 PIN 4: -Vout
 PIN 5: N/C
 PIN 6: N/C
 PIN 7: N/C
 PIN 8: N/C

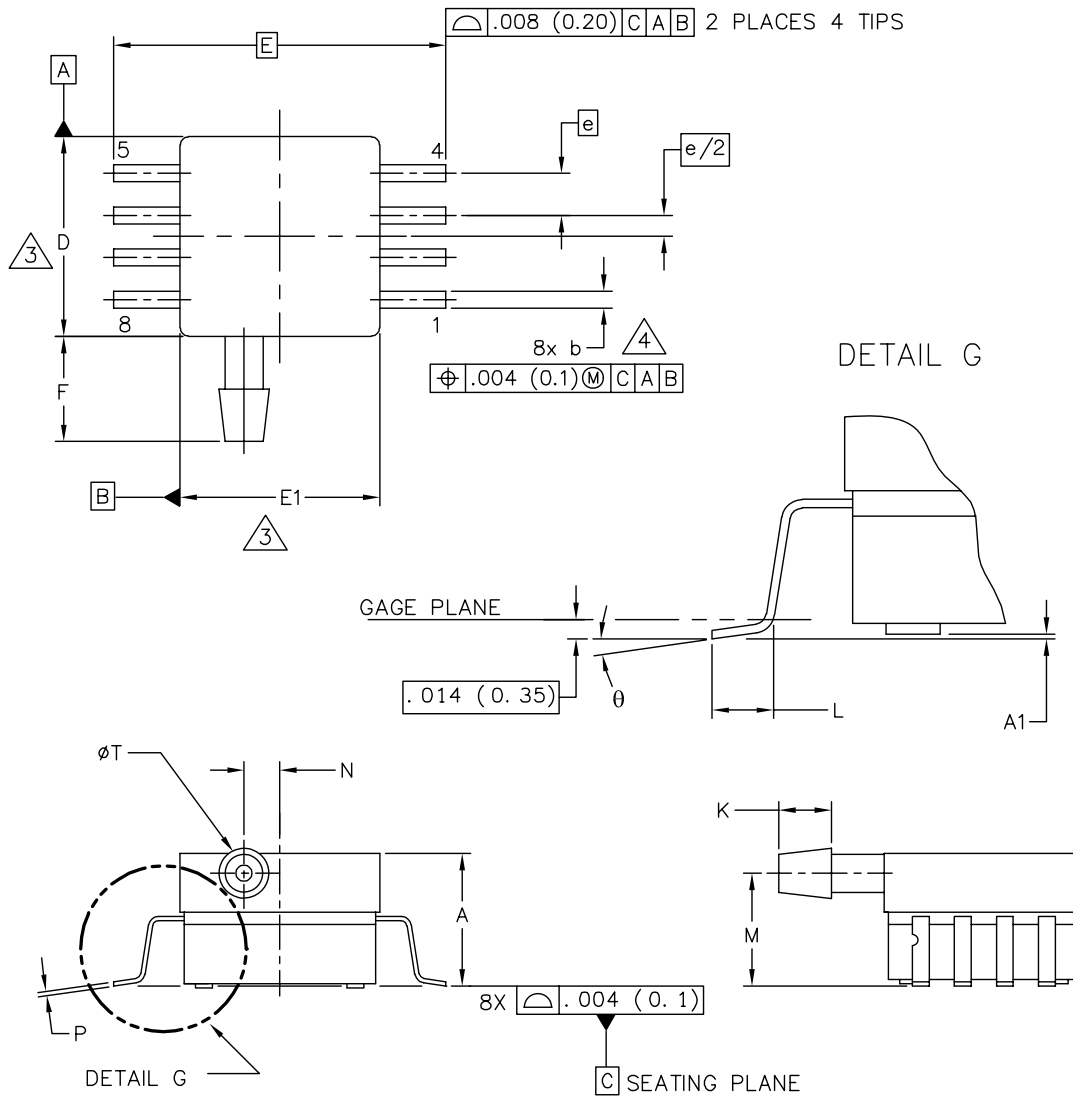
STYLE 2:

PIN 1: N/C
 PIN 2: Vs
 PIN 3: GND
 PIN 4: Vout
 PIN 5: N/C
 PIN 6: N/C
 PIN 7: N/C
 PIN 8: N/C

© FREESCALE SEMICONDUCTOR, INC. ALL RIGHTS RESERVED.	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE	
TITLE: 8 LD SNSR, DUAL PORT	DOCUMENT NO: 98ASA99255D	REV: A	
	CASE NUMBER: 1351-01	27 JUL 2005	
	STANDARD: NON-JEDEC		

**CASE1351-01
 ISSUE A
 SMALL OUTLINE PACKAGE**

PACKAGE DIMENSIONS



© FREESCALE SEMICONDUCTOR, INC. ALL RIGHTS RESERVED.	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE	
TITLE: 8 LD SOP, SIDE PORT	DOCUMENT NO: 98ASA99303D	REV: B	
	CASE NUMBER: 1369-01	24 MAY 2005	
	STANDARD: NON-JEDEC		

**CASE 1369-01
ISSUE B
SMALL OUTLINE PACKAGE**

PACKAGE DIMENSIONS

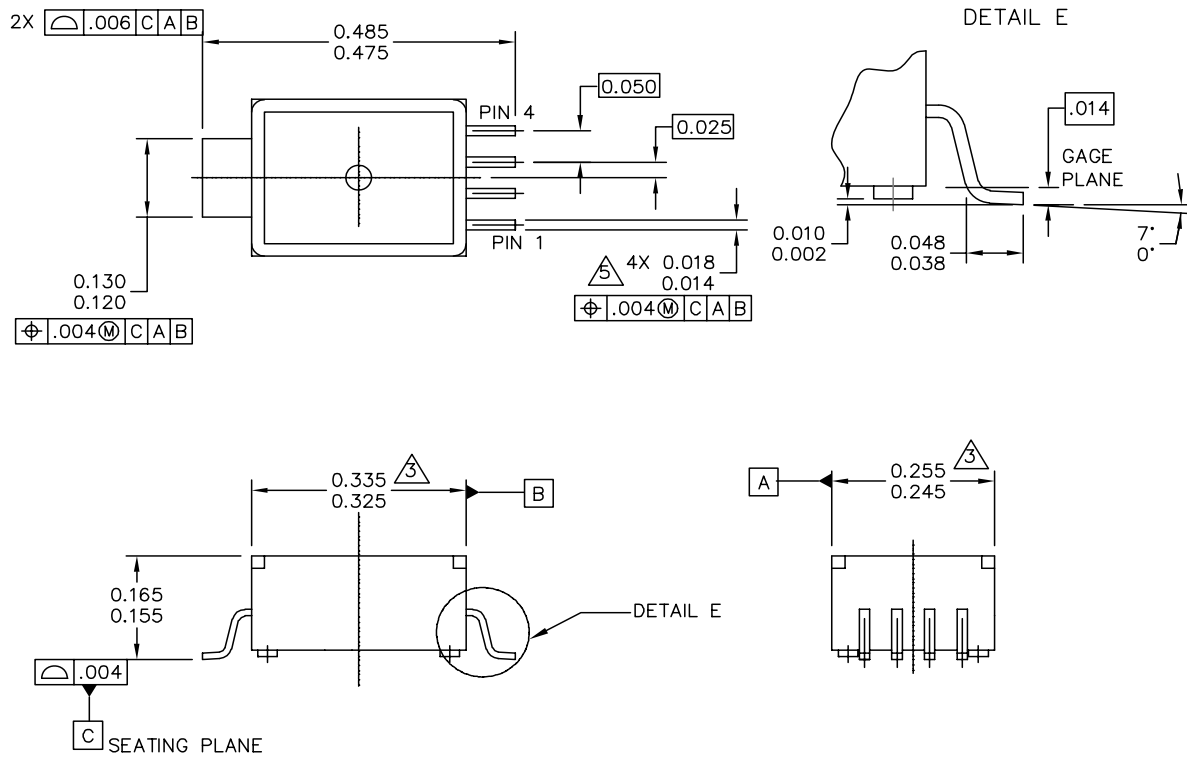
NOTES:

1. CONTROLLING DIMENSION: INCH
 2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
- ⚠ DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH AND PROTRUSIONS SHALL NOT EXCEED .006 (0.152) PER SIDE.
- ⚠ DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE .008 (0.203) MAXIMUM.

DIM	INCHES		MILLIMETERS		DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX
A	.300	.330	7.11	7.62	θ	0°	7°	0°	7°
A1	.002	.010	0.05	0.25	-	---	---	---	---
b	.038	.042	0.96	1.07	-	---	---	---	---
D	.465	.485	11.81	12.32	-	---	---	---	---
E	.717 BSC		18.21 BSC		-	---	---	---	---
E1	.465	.485	11.81	12.32	-	---	---	---	---
e	.100 BSC		2.54 BSC		-	---	---	---	---
F	.245	.255	6.22	6.47	-	---	---	---	---
K	.120	.130	3.05	3.30	-	---	---	---	---
L	.061	.071	1.55	1.80	-	---	---	---	---
M	.270	.290	6.86	7.36	-	---	---	---	---
N	.080	.090	2.03	2.28	-	---	---	---	---
P	.009	.011	0.23	0.28	-	---	---	---	---
T	.115	.125	2.92	3.17	-	---	---	---	---
© FREESCALE SEMICONDUCTOR, INC. ALL RIGHTS RESERVED.			MECHANICAL OUTLINE			PRINT VERSION NOT TO SCALE			
TITLE: 8 LD SOP, SIDE PORT					DOCUMENT NO: 98ASA99303D			REV: B	
					CASE NUMBER: 1369-01			24 MAY 2005	
					STANDARD: NON-JEDEC				

**CASE 1369-01
ISSUE B
SMALL OUTLINE PACKAGE**

PACKAGE DIMENSIONS



© FREESCALE SEMICONDUCTOR, INC. ALL RIGHTS RESERVED.	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE	
TITLE: 5 LD M-PAC	DOCUMENT NO: 98ARH99088A	REV: B	
	CASE NUMBER: 1320-02	22 JUL 2005	
	STANDARD: NON-JEDEC		

**CASE 1320-02
ISSUE B
MPAK**

PACKAGE DIMENSIONS

NOTES:

- 1. DIMENSIONS ARE IN INCHES.
- 2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.

△3 DIMENSION DOES NOT INCLUDE MOLD FLASH OR PROTRUSION. MOLD FLASH OR PROTRUSION SHALL NOT EXCEED .006" PER SIDE.

- 4. ALL VERTICAL SURFACES TO BE 5° MAXIMUM.

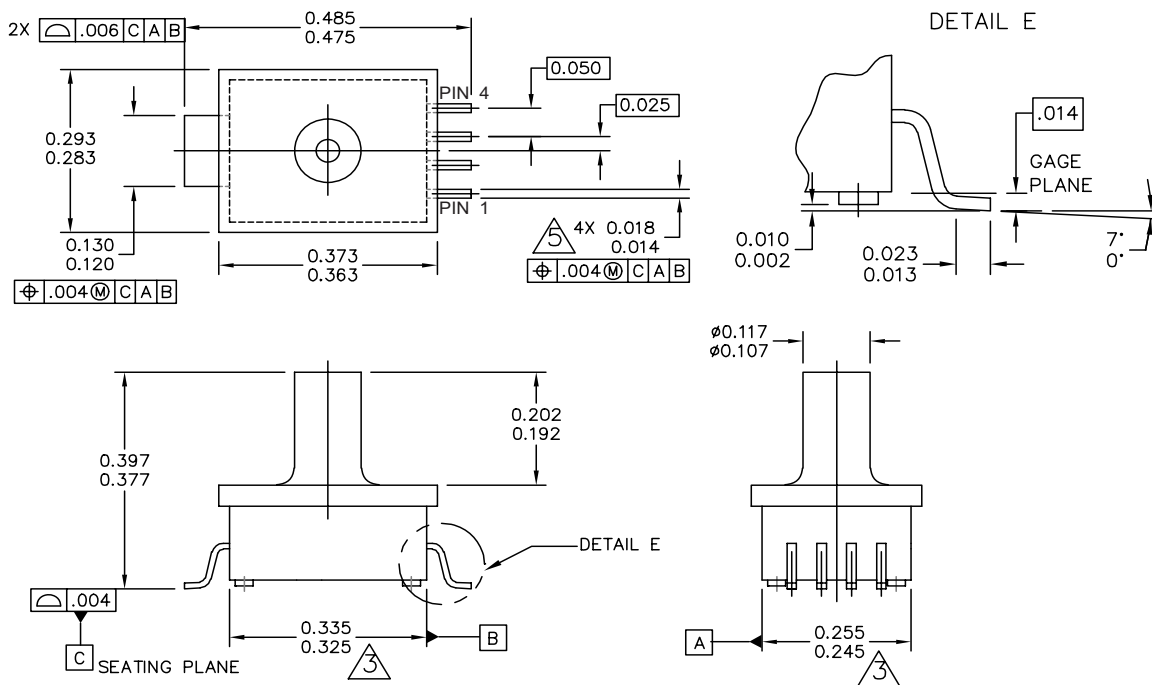
△5 DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE .008 MAXIMUM.

PIN 1: GND
 PIN 2: +Vout
 PIN 3: Vs
 PIN 4: -Vout

© FREESCALE SEMICONDUCTOR, INC. ALL RIGHTS RESERVED.	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE	
TITLE: 5 LD M-PAC	DOCUMENT NO: 98ARH99088A	REV: B	
	CASE NUMBER: 1320-02	22 JUL 2005	
	STANDARD: NON-JEDEC		

**CASE 1320-02
 ISSUE A
 MPAK**

PACKAGE DIMENSIONS



© FREESCALE SEMICONDUCTOR, INC. ALL RIGHTS RESERVED.	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE	
TITLE: 5 LD M-PAC, PORTED	DOCUMENT NO: 98ARH99087A	REV: A	
	CASE NUMBER: 1320A-02	22 JUL 2005	
	STANDARD: NON-JEDEC		

**CASE 1320A-02
ISSUE A
MPAK**

PACKAGE DIMENSIONS

NOTES:

1. DIMENSIONS ARE IN INCHES.

2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.

3. DIMENSIONS DOES NOT INCLUDE MOLD FLASH OR PROTRUSION. MOLD FLASH OR PROTRUSION SHALL NOT EXCEED .006" PER SIDE.

4. ALL VERTICAL SURFACES TO BE 5" MAXIMUM.

5. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE .008 MAXIMUM.

© FREESCALE SEMICONDUCTOR, INC. ALL RIGHTS RESERVED.	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE	
TITLE: 5 LD M-PAC, PORTED		DOCUMENT NO: 98ARH99087A	REV: A
		CASE NUMBER: 1320A-02	22 JUL 2005
		STANDARD: NON-JEDEC	

**CASE 1320-02
ISSUE A
MPAK**

How to Reach Us:

Home Page:

www.freescale.com

Web Support:

<http://www.freescale.com/support>

USA/Europe or Locations Not Listed:

Freescale Semiconductor, Inc.
Technical Information Center, EL516
2100 East Elliot Road
Tempe, Arizona 85284
1-800-521-6274 or +1-480-768-2130
www.freescale.com/support

Europe, Middle East, and Africa:

Freescale Halbleiter Deutschland GmbH
Technical Information Center
Schatzbogen 7
81829 Muenchen, Germany
+44 1296 380 456 (English)
+46 8 52200080 (English)
+49 89 92103 559 (German)
+33 1 69 35 48 48 (French)
www.freescale.com/support

Japan:

Freescale Semiconductor Japan Ltd.
Headquarters
ARCO Tower 15F
1-8-1, Shimo-Meguro, Meguro-ku,
Tokyo 153-0064
Japan
0120 191014 or +81 3 5437 9125
support.japan@freescale.com

Asia/Pacific:

Freescale Semiconductor China Ltd.
Exchange Building 23F
No. 118 Jianguo Road
Chaoyang District
Beijing 100022
China
+86 010 5879 8000
support.asia@freescale.com

For Literature Requests Only:

Freescale Semiconductor Literature Distribution Center
P.O. Box 5405
Denver, Colorado 80217
1-800-441-2447 or +1-303-675-2140
Fax: +1-303-675-2150
LDCForFreescaleSemiconductor@hibbertgroup.com

Information in this document is provided solely to enable system and software implementers to use Freescale Semiconductor products. There are no express or implied copyright licenses granted hereunder to design or fabricate any integrated circuits or integrated circuits based on the information in this document.

Freescale Semiconductor reserves the right to make changes without further notice to any products herein. Freescale Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does Freescale Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation consequential or incidental damages. "Typical" parameters that may be provided in Freescale Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals", must be validated for each customer application by customer's technical experts. Freescale Semiconductor does not convey any license under its patent rights nor the rights of others. Freescale Semiconductor products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the Freescale Semiconductor product could create a situation where personal injury or death may occur. Should Buyer purchase or use Freescale Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold Freescale Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that Freescale Semiconductor was negligent regarding the design or manufacture of the part.

Freescale™ and the Freescale logo are trademarks of Freescale Semiconductor, Inc. All other product or service names are the property of their respective owners.

© Freescale Semiconductor, Inc. 2008. All rights reserved.

